

## KIWOMASK® W 850 Etch

### Screen printable etching and sputtering resist

KIWOMASK W 850 Etch is a one-component screen-printing lacquer which is resistant in acid etching baths. Furthermore, it is suitable for the partial covering of glass in plasma processes (sputtering). Its thixotropic formulation facilitates high-definition printing of finest details and lines.

#### APPLICATION

Pre-treatment: Make sure the substrate is clean and free from grease for optimum adhesion.

KIWOMASK W 850 Etch is being applied by screen printing and cured by heat.

Recommended screen-printing parameters: Polyester mesh 120-34 Y or corresponding steel mesh, solvent resistant screen-printing emulsion.

#### DRYING

Depending on the applied thickness, approx. 60-90 minutes at 60-80°C, or in a suitable in-line dryer at a maximum of 160°C.

Notice: Due to the varying types of etching baths, it is essential to carry out tests in your own facilities.

#### REDUCING/ REDARDING

KIWOSOLV L 82

Ready-to-use product, dilution is not recommended. When having longer printing breaks, we recommend using KIWOSOLV L 82 as retarder. Add approx. 3-5%.

#### CLEANING

Commercially available organic solvent-based cleaners

Stripping of the resist: at ambient temperature with caustic soda or caustic potash solution (3-5%), or by using the ready-to-use solution PREGASOL R 800.

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#### COLOUR

Red

#### VISCOSITY

Approx. 6.500 mPas

#### HEALTH HAZARDS/ ENVIRONMENTAL PROTECTION

Please follow further information given in the material safety data sheet.

#### STORAGE

12 months (at 20 - 25°C and original container). Protect against freezing and direct sun light.